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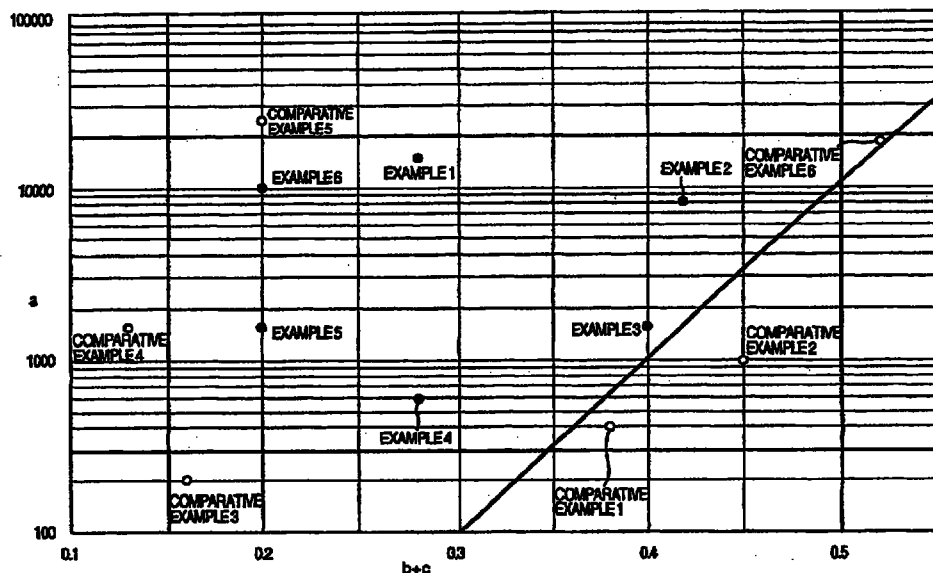
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(54) Title: EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE



(57) Abstract: The present invention provides an epoxy resin composition for encapsulating of semiconductors which is suitable for area mounting type semiconductor devices and is less in warping and excellent in soldering crack resistance. The epoxy resin composition comprises (A) an epoxy resin, (B) a phenolic resin, (C) a curing accelerator and (D) an inorganic filler as main components, where properties of a cured product formed by heating and curing the epoxy resin composition satisfy expressions, $a \geq 10^R$ ($R = 10 \times (b + c) - 1$), $300 \leq a \leq 20000$ and $0.15 \leq b + c \leq 0.50$ in which a denotes a flexural modulus (N/mm²) at molding temperature, b denotes a cure shrinkage (%) and c denotes a heat shrinkage (%) of from molding temperature to room temperature.

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